

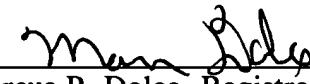
Applicant : Ralph Beyer et al.
For : LARGE PACKAGE FOR THE TRANSPORT AND STORAGE OF
INSULATION ELEMENTS AND COMBINED IN MODULES
THEREFOR
Page : 14

REMARKS

Applicants have attempted to place the claims and specification into conformity with the United States patent claim and application format. Applicants therefore respectfully submit that all pending claims are in condition for allowance, and a Notice to this effect is earnestly solicited.

Respectfully submitted,

10/13/05
Date


Marcus P. Dolce, Registration No. 46 073
Price, Heneveld, Cooper, DeWitt & Litton, LLP
695 Kenmoor, S.E.
Post Office Box 2567
Grand Rapids, Michigan 49501
(616) 949-9610

MPD/msj